

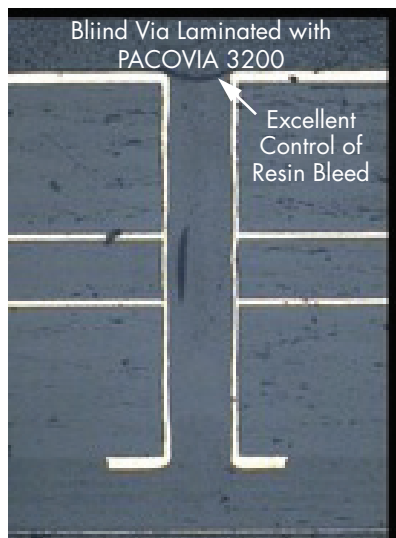
## High Performance, Resin-Blocking, Release Film



### **PACO•VIA 3200 IMPROVED RESIN-BLOCKING SYSTEM**

**For the Lamination of Blind and Buried Via Holes**

**PACO•VIA 3200™** is an engineered newly improved conformal release film specifically designed to provide an easy and reliable technique for laminating multilayer printed circuit boards which incorporates buried and blind via hole technology. PACO•VIA 3200 enhances sequential lamination of buried and blind via designed rigid multilayer printed circuit boards.



#### **LAMINATION PROCESS ADVANTAGES:**

##### **Resin Containment**

**PACO•VIA 3200** resin blocking film contains the resin in the via barrel minimizing the need for aggressive secondary processing to remove cured resin from the panel surface.

##### **Barrel Fill**

**PACO•VIA 3200** resin blocking film allows the liquid resin under High Temperature (425°F/218°C) to essentially fill the Via Barrel

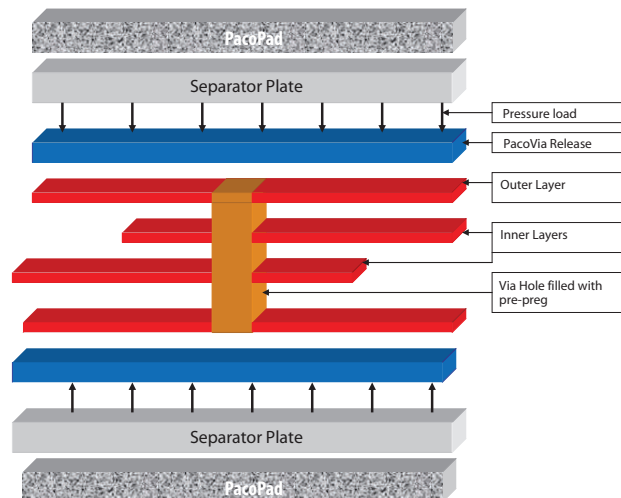
##### **Contain Resin Squeeze-out**

**PACO•VIA 3200** resin blocking film contains resin squeeze-out better than traditional release films offering superior copper surface buffering from damaged or inferior lamination plates.

#### **PACO•VIA 3200 SYSTEM FEATURES:**

##### **Equalization of pressure throughout the Press Load**

The **PACO•VIA 3200** resin blocking film system features the use of Pacopads on the outside of the lamination make-up top and bottom. PACOPAD is placed adjacent to the steel separator plate which is followed by PACO•VIA 3200 on the other side adjacent to the blind via circuit. PACOPAD, as the second component, ensures macro z-axis pressure distribution that allows PACO•VIA 3200 resin blocking film to perform micro z-axis conformability achieving complete barrel fill and controlled dielectric thickness on the blind via circuit. All of these attributes reflect the consistent performance standards engineered into Paco•Via 3200 to optimize your Blind Via manufacturing process.



## **PERFORMANCE SPECIFICATIONS**

- **Operating temperature of 425°F/218°C for up to four hours**
- **Thickness gauge of film is .003"/76µ**
- **Suitable for Polyimide applications or standard resin systems**
- **Essentially inert, no outgassing, plate residue, interlaminar adhesion influence, no vacuum system contamination**

## **WIDE PROCESS WINDOW:**

- The PACO•VIA 3200 system is designed to contain resin flow within blind via holes (onto adjacent copper-carrying layers) and to fill buried via barrels under a wide range of lamination pressures (175-350PSI/12-24 kg/cm<sup>2</sup>), via hole diameters range (.004 to .040"/.01 to 1.0mm) and heat rises and pre-pregs of varying types.
- Improved formulation makes PACO•VIA 3200 an easier to handle film for operators with considerable less tackiness.
- The PACO•VIA 3200 system performs effectively well in hydraulic and hydraulic vacuum-assist lamination presses.
- Stainless steel separators are preferred but aluminum separator plates are acceptable.  
See PACOTHANE TECHNOLOGIES Lay-up Product Information Bulletin.

## **AVAILABILITY**

PACO•VIA 3200 is available in rolls or custom sized sheets, tooled to customer specifications.

The complete line of Lamination Enhancements Products listed below are available from leading local distributors worldwide who offer "just in time" delivery from locally available stocks.

### **RELEASE PRODUCTS**



### **PRESS PADS**



### **APPLICATION SPECIFIC**



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